



Package Chemistry Substances Analysis Table

Package Type:	SOIC 008
Dimensions:	5.28 x 5.28 x 1.95 mm
Weight of Unit Package:	123.5 mg
Temperature rating:	260°C
MSL:	3
Assembly Location:	UTAC
	Product is RoHS Compliant

Description	Chemicals Present	CAS Number	unit weight (mg)	unit weight/package (%)	Amount (ppm)
Silicon Die	#1 Silicon	7440-21-3	1.4801	1.1981	11,981
	subtotal		1.4801	1.1981	11,981
Bond Wire	#1 Copper	7440-50-8	0.0346	0.0280	280
	#2 Palladium	7440-05-3	0.0006	0.0005	5
subtotal			0.0352	0.0285	285
Die Attach Film	#1 Silver	7440-22-4	0.1804	0.1461	1,461
	#2 Isobornyl methacrylate	7534-94-3	0.0334	0.0271	271
	#3 N,N'-1,3-Phenylene bismaleimide	3006-93-7	0.0089	0.0072	72
	#4 Acrylic acid, 2-[Methyl[(1,1,2,2,3,3,4,4,4-nonafluorobutyl)sulfonyl]amino]ethyl ester, telomer with 3-mercapto-1,2-propanediol,2-me	1017237-78-3	0.0001	0.0001	1
subtotal			0.2229	0.1804	1,804
Leadframe	#1 Copper	7440-50-8	53.6555	43.4317	434,317
	#2 Iron	7439-89-6	1.2260	0.9924	9,924
	#3 Phosphorus	7723-14-0	0.0192	0.0156	156
	#4 Zinc	7440-66-6	0.0759	0.0614	614
subtotal			54.9766	44.5011	445,011
Internal Plating	#1 Silver Plating (Internal)	7440-22-4	1.1220	0.9082	9,082
subtotal			1.1220	0.9082	9,082
Mold compound	#1 Silica fused	60676-86-0	51.3055	41.5295	415,295
	#2 Epoxy resin	Trade Secret	3.5383	2.8641	28,641
	#3 Epoxy, Cresol Novolac	29690-82-2	1.1794	0.9547	9,547
	#4 Phenol Resin	Trade Secret	2.8896	2.3390	23,390
	#5 Carbon Black	1333-86-4	0.0590	0.0477	477
subtotal			58.9718	47.7350	477,350
External Plating	#1 Matte tin	7440-31-5	6.7314	5.4487	54,487
subtotal			6.7314	5.4487	54,487
PACKAGE TOTAL			123.5400	100.0000	1,000,000

Disclaimer:

In general, four decimal values are shown. However, some variance remains from package to package. The mass values presented are thought to be accurate to within 20 percent. The report does not include materials not intentionally added to our products (impurities), or material concentrations less than 1 ppm.

Document History Page

Document Title: Material Declaration Datasheet (MDDS) - SOIC008 (SOC008) - UTAC - CuPd Wire
Document Number: 002-13001

Rev.	ECN No.	Orig. of Change	Description of Change
**	5272579	AAC	Initial Release.